



Material Content Data Sheet



Halogen-Free

Sales Product Name	IPD050N10N5	Issued	10. May 2021
MA#	MA001619248		
Package	PG-TO252-3-313	Weight*	319.49 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	2.258	0.71	0.71	7067	7067
leadframe	inorganic material	phosphorus	7723-14-0	0.044	0.01		138	
	non noble metal	iron	7439-89-6	0.147	0.05		461	
	non noble metal	copper	7440-50-8	147.096	46.05	46.11	460412	461011
wire	non noble metal	aluminium	7429-90-5	5.156	1.61	1.61	16138	16138
encapsulation	inorganic material	zinc oxide	1314-13-2	1.382	0.43		4326	
	miscellaneous	miscellaneous	-	6.911	2.16		21630	
	plastics	epoxy resin	-	20.732	6.49		64891	
	inorganic material	silicon dioxide	60676-86-0	109.187	34.18	43.26	341757	432604
lead finish	non noble metal	tin	7440-31-5	3.740	1.17	1.17	11706	11706
plating	inorganic material	phosphorus	7723-14-0	0.003			11	
	non noble metal	nickel	7440-02-0	1.421	0.44	0.44	4446	4457
solder	non noble metal	tin	7440-31-5	0.044	0.01		138	
	noble metal	silver	7440-22-4	0.055	0.02		173	
	non noble metal	lead	7439-92-1	2.109	0.66	0.69	6602	6913
heatspreader	inorganic material	phosphorus	7723-14-0	0.006			18	
	non noble metal	iron	7439-89-6	0.019	0.01		60	
	non noble metal	copper	7440-50-8	19.177	6.00	6.01	60026	60104
*deviation	< 10%	Sum in total:				100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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